

HSB2838

Silicon Epitaxial Planar Diode for High Speed Switching

REJ03G0549-0200 (Previous: ADE-208-486A) Rev.2.00 Mar 04, 2005

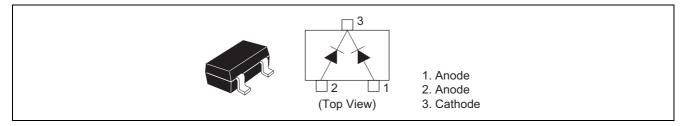
## Features

- Fast recovery time.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

## **Ordering Information**

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSB2838	A6	СМРАК	PTSP0003ZB-A (CMPAK)

## **Pin Arrangement**





# **Absolute Maximum Ratings**

			$(Ta = 25^{\circ}C)$
Item	Symbol	Value	Unit
Peak reverse voltage	V <sub>RM</sub>	85	V
Reverse voltage	V <sub>R</sub>	80	V
Peak forward current	I <sub>FM</sub> * <sup>1</sup>	300	mA
Non-Repetitive peak forward surge current	I <sub>FSM</sub> * <sup>2</sup>	4	А
Average rectified current	lo * <sup>1</sup>	100	mA
Junction temperature	Тј	125	°C
Storage temperature	Tstg	-55 to +125	٥C

Notes: 1. Two device total.

2. Value at duration of 1  $\mu$ s, two device total.

# **Electrical Characteristics \***

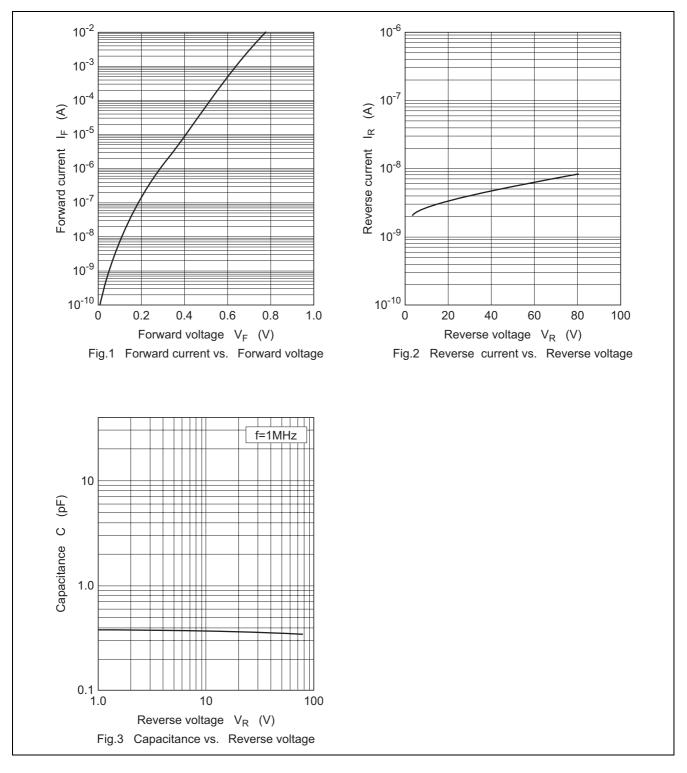
 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V <sub>F1</sub>	—	_	1.0	V	I <sub>F</sub> = 10 mA
	V <sub>F2</sub>	—	_	1.0		I <sub>F</sub> = 50 mA
	$V_{F3}$	—	_	1.2		I <sub>F</sub> = 100 mA
Reverse current	I <sub>R</sub>	—	_	0.1	μΑ	V <sub>R</sub> = 80 V
Capacitance	С	—	_	2.0	pF	$V_R = 0 V$ , f = 1 MHz
Reverse recovery time	t <sub>rr</sub>	_	_	3.0	ns	$I_F=10~mA,~V_R=6~V,~R_L=50~\Omega$

Note: Per one device.

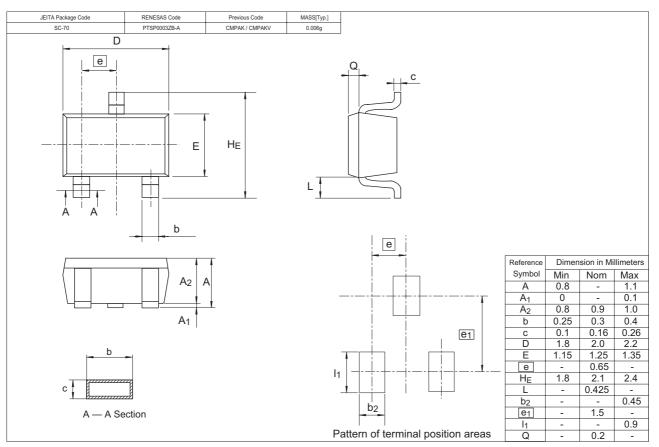


# **Main Characteristic**





# Package Dimensions





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